



Physical Interface & Carriers Global Technical Committee Japan TC Chapter Meeting

Japan Standards Fall Meetings 2025
Friday, September 26, 2025
Official Virtual TC Chapter Meeting & SEMI Japan office [Hybrid]
10:00am - 1:00pm JST

AGENDA

1. **Welcome / Call to Order**
 - 1.1 Introductions
 - 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
 - 1.3 Agenda Review

2. **Review of Previous Meeting Minutes**

3. **Liaison Report**
 - 3.1 North America
 - 3.2 JRSC

4. **Staff Report**

5. **Ballot Review**

#	When	TF	Details
7373	Cycle 6, 2025	Panel Level Packaging (PLP) Panel FOUN Task Force	Line Item Revision to SEMI E182-0424 - Specification for Panel FOUN Loadport for Panel Level Packaging
7374	Cycle 6, 2025	Panel Level Packaging (PLP) Panel FOUN Task Force	Revision to add a new Subordinate Standard: SPECIFICATION FOR PANEL FOUN LOAD PORT WITH GROUND BASED DELIVERY EXCLUSION VOLUME to SEMI E182-0424 SPECIFICATION FOR PANEL FOUN LOADPORT FOR PANEL LEVEL PACKAGING

6. **Approval of Preliminary Standard**
 - 6.1 Doc. 7375, New Preliminary Standard: Specification for Large Tray Stack FOUN (LTSF)
7. **Subcommittee & Task Force Reports**
 - 7.1 Global PIC Standards Maintenance TF
 - 7.2 Japan Electron Microscopy Workflow liaison TF
 - 7.3 Panel Level Packaging Panel FOUN TF
 - 7.4 Next Gen Assembly / Test Material Handling TF
 - 7.5 [Liaison: 3D Packaging & Integration JA TCC] Panel Level Packaging Glass Carrier TF
 - 7.6 [Liaison: 3D Packaging & Integration NA TCC] Panel Level Packaging Panel TF
8. **Old Business**
 - 8.1 Project Period Review
 - 8.2 5 Year Review

9. New Business

9.1 SNARF Cancellation

9.1.1 Document #7172: New Standard: Specification for Next Gen Assembly / Test Carrier

9.1.2 Document #7333: Revision to add a new Subordinate Standard, SPECIFICATION FOR PANEL FOUP LOADPORT GROUND BASED VEHICLE DELIVERY EXCLUSION VOLUME to SEMI E182 SPECIFICATION FOR PANEL FOUP LOADPORT FOR PANEL LEVEL PACKAGING

9.2 TFOF Approval

9.2.1 Square 310mm FOUP Task Force

9.3 SNARF Approval

9.3.1 Line item revision to SEMI E181.1 — Specification for Panel FOUP for 510 to 515 mm Panel Size and 12 Slots, SEMI E181.2 — Specification for Panel FOUP for 510 to 515 mm Panel Size and 6 Slots, SEMI E181.3 — Specification for Panel FOUP for 600 to 600 mm Panel Size and 12 Slots and SEMI E181.4 — Specification for Panel FOUP for 600 to 600 mm Panel Size and 6 Slots

10. Action Item Review

9.1 Open Action Items

#	Assigned to	Details
PIC_20250418-1	SEMI Staff	Ask Minutes format update for the part of leader change to HQ
PIC_20250418-2	SEMI Staff	Doc#6896: Contact HQ to get the details (what we do for future)

9.2 New Action Items

#	Assigned to	Details

11. Next Meeting and Adjournment